ABSTRACT OF THE DISCLOSURE

The present invention relates to a solder joint life prediction method for predicting the joint life of joining solder which joins members with each other. It predicts the life of soldered joints with high accuracy in a short period of time. It observes phase growth in a crack pre-initiation stage, extrapolates the phase growth, and thereby predicts the time of crack initiation when an initial crack will appear in the joining solder. After the crack initiation, the present invention predicts the time of fracture using a simulation in which creep analysis is performed with a virtual initial crack given to data-based joining solder.